



**Correction**  
**CUSTOMER PRODUCT-/ PROCESS CHANGE NOTIFICATION**

Reactions to this notifications are to be adressed to your local Philips sales representative or quality contact.

<b>CPCN Number:</b> 200305025C		<b>CPCN Issue Date:</b> Nov 16 2004	
<b>Author:</b> Maas Geesteranus, Michiel in Nijmegen		<b>Issued by:</b> Maas Geesteranus, Michiel in Nijmegen	
<b>Previous Notifications:</b> May 28, 2003: 200305025 Advance Nov 05, 2003: 200305025F Final Dec 16, 2003: 200305025S Supplement			
<b>Change Affects a Whole Prod/Proc/Pkg Family?</b> No		<b>IC Application Area:</b> In Multiple IC Areas	
<b>Product Types/12ncs Affected:</b>			
12NC	12NC (New)	Type Number	Type Number (New)
999999999999		FOR THE TYPelist	SEE THE WEBPAGE #
			INDICATED BELOW
			UNDER REMARKS
<b>Change Category:</b> ASSEMBLY/SITE/PACKAGE/MATERIAL <b>Change Description:</b> Original Advance CPCN 200305025 text (May 2003): Lead (Pb) containing leadfinish material will be replaced by a lead(Pb)-free leadfinish material, starting from October 1st, 2003 onwards.  For the specific subject this time: See the texts below.			
<b>Reason for Change:</b> Increased environmental friendliness, forced by world-wide programs and legislation to ban out lead (Pb) from semiconductor packages. Additional for this correction CPCN: 1. Improve MSL performance at 260 °C per J-STD 020C. 2. Meet the future environmental requirement for antimony-oxide-free and halogene-free materials.			
<b>Remarks:</b> The "Attachment" below contains following information (in a ZIP file): 1. Qualification plan for the related packages 2. Type list for the related product types For all other (up-to-date) information about the leadfree program a webpage has been created: <a href="http://www.semiconductors.com/green_roadmap/">http://www.semiconductors.com/green_roadmap/</a> .			
<b>Correction To:</b> Die attach and moulding compound for SSOP/TSSOP/HTSSOP packages produced at Amkor Philipines (ATP). There are 2 changes to be made: 1) The original plan was to convert to matt sn as interim solution and then to NiPdAu as a final solution. The new plan is to convert straight to NiPdAu. 2) The original plan was to use standard die attach and moulding compound. The new plan is to use more environmentally friendly die attach and moulding compound. (SSOP family: Ablestik Ablebond 8290 die-attach + Sumitomo EMEG600 mold compound, TSSOP/HTSSOP family: Ablestik Ablebond 8290 die-attach + Sumitomo EMEG700 mold compound) Production of related products with the new materials will start from March 2005 onwards.			
<b>Attachment:</b> Self Qualification Plan and Product Type List.			



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<b>Approved by:</b>	<b>Name:</b>	<b>Job Title:</b>	<b>Date:</b>
	Eef Bagerman	Sr. Director ATO Innovation	Nov 16 2004
	Rob de Heus	Leadfree Program Manager	Nov 16 2004
	Michiel Maas Geesteranus	Assembly Technical Change Coordinator ATO I	Nov 16 2004

An approved electronic or hardcopy version of this Change Notification has been filed by the publishing Business Unit or Business Line/Orgnaization mentioned at the top of this document.



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